

Do 09-22-2009

Form 1



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FORM COVER SHEET

U.S. Department of Commerce
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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies):

Names(s)	Date of Execution
Huang, Lee-May,	August 10, 2009
Peng, Cheng-Yu,	August 10, 2009
Liang, Wen-Chung,	August 3, 2009
Chen, Chun-Heng,	August 6, 2009

2. Name/address of receiving Party(ies):

Industrial Technology Research Institute

No. 195, Sec. 4, Chung Hsing Rd.,
Chutung, Hsinchu 31040, Taiwan,
R. O. C.

3. Nature of conveyance: Assignment
 Merger Security Agreement Other
 Change of Name Reassignment

Add'l name(s)/address(es) of receiving parties
Attached? Yes No

4. Application number(s) or patent number(s):

A. Patent Application No. (s)

12 584693

Additional numbers attached?

B. Patent No. (s)

Yes No

5. Name and address of party to whom Correspondence concerning document should be mailed:

J. C. Patents
4, Venture Suite 250
Irvine, CA. 92618
Tel: (949) 660-0761
Fax: (949) 660-0809
E-mail: jcpi@email.msn.com

6. Total No. of applications and patents involved:

ONE(1)

7. Total fee (37 CFR §3.41): \$40.00

- Authorized to be charge by credit card
 Authorized to be charge to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last Numbers _____
Expiration Date _____
b. Deposit Account Number 50-0710
Authorized User Name Jiawei Huang

Atty Docket No.: JCLA28695

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

09/21/2009 DBYRNE 00000048 500710 12584693

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Jiawei Huang
Name of Person Signing
Registration No. 43,330

Signature

9-9-2009
Date

Total number of pages
including cover sheet,
attachments, and
documents: 3

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28695-US-PA

ASSIGNMENT

WHEREAS,

- | | |
|---------------------|--------------------|
| 1. Huang, Lee-May | 2. Peng, Cheng-Yu |
| 3. Liang, Wen-Chung | 4. Chen, Chun-Heng |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **ENCAPSULANT MATERIAL, CRYSTALLINE SILICON PHOTOVOLTAIC MODULE AND THIN FILM PHOTOVOLTAIC MODULE**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R. O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Huang, Lee-May
Sole or First Joint Inventor: Huang, Lee-May

Date: 2009. 8. 10

Signature: Peng, Cheng-Yu
Second Joint Inventor (if any): Peng, Cheng-Yu

Date: 2009. 8. 10.

Signature: Liang, Wen-chung
Third Joint Inventor (if any): Liang, Wen-Chung

Date: 2009 8. 3

Signature: Chen, Chun-Heng
Fourth Joint Inventor (if any): Chen, Chun-Heng

Date: 2009. 8. 6